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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











DGD2104

HALF-BRIDGE GATE DRIVER IN SO-8

Description

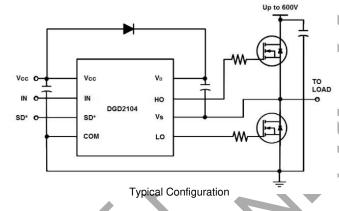
The DGD2104 is a high-voltage / high-speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. High-voltage processing techniques enable the DGD2104's high side to switch to 600V in a bootstrap operation.

The DGD2104 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction. The DGD2104 has a fixed internal deadtime of 520ns (typical).

The DGD2104 is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Features

- Floating High-Side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuration
- 290mA Source / 600mA Sink Output Current Capability
- Outputs Tolerant to Negative Transients
- Internal Dead Time of 520ns to Protect MOSFETs
- Wide Low-Side Gate Driver Supply Voltage: 10V to 20V
- Logic Input (IN and SD*) 3.3V Capability
- Schmitt Triggered Logic Inputs
- Undervoltage Lockout for V_{CC} (Logic and Low Side Supply)
- Extended Temperature Range: -40°C To +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)



SO-8 (Type TH)
Top View

Ordering Information (Note 4)

Ī	Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
	DGD2104S8-13	DGD2104	13	12	2,500

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

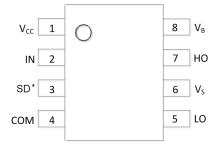


O;; = Manufacturer's Marking
DGD2104 = Product Type Marking Code
YY = Year (ex: 16 = 2016)
WW = Week (01 to 53)



DGD2104

Pin Diagrams

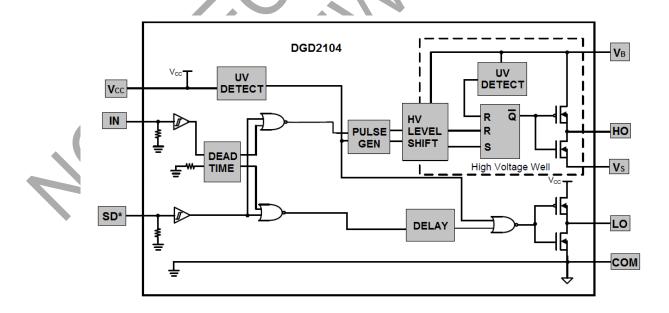


Top View: SO-8 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	Vcc	Logic and Low Side Supply
2	IN	Logic Input for High-Side and Low-SideGate Driver Outputs (HO and LO), in Phase with HO
3	SD*	Logic input for Shutdown, Enabled Low
4	COM	Low-Side and Logic Return
5	LO	Low-Side Gate Drive Output
6	Vs	High-Side Floating Supply Return
7	НО	High-Side Gate Drive Output
8	V _B	High-Side Floating Supply

Functional Block Diagram



NOT RECOMMENDED FOR NEW DESIGN USE DGD2104M



DGD2104

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V _B	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V_S -0.3 to V_B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Low-Side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (IN and SD*)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear derating factor (Note 5)	P _D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	TL	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V_{B}	V _S + 10	V _S + 20	V
High Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High Side Floating Output Voltage	V _{HO}	Vs	V_{B}	V
Low Side Fixed Supply Voltage	V _{CC}	10	20	V
Low Side Output Voltage	V_{LO}	0	V _{CC}	V
Logic Input Voltage (IN and SD*)	V_{IN}	0	5	V
Ambient Temperature	Ta	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to - V_{BS} .

NOT RECOMMENDED FOR NEW DESIGN USE DGD2104M



DGD2104

$\textbf{DC Electrical Characteristics} \ (V_{BIAS} \ (V_{CC}, \ V_{BS}) = 15V, \ @T_A = +25^{\circ}C, \ unless \ otherwise \ specified.) \ (Note \ 7)$

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Logic "1" (IN) & Logic "0" (SD*) Input Voltage	V_{IH}	2.5	ı	ı	V	V _{CC} = 10V to 20V
Logic "0" (IN) & Logic "1" (SD*) Input Voltage	V_{IL}	_	-	0.8	V	V _{CC} = 10V to 20V
High Level Output Voltage, V _{BIAS} - V _O	V _{OH}	_	0.05	0.2	V	I _O = 2mA
Low Level Output Voltage, V _O	V_{OL}	_	0.02	0.1	V	$I_O = 2mA$
Offset Supply Leakage Current	I_{LK}	-	ı	50	μΑ	$V_B = V_S = 600V$
Quiescent V _{BS} Supply Current	I_{BSQ}	_	60	100	μΑ	$V_{IN} = 0V \text{ or } 5V$
Quiescent V _{CC} Supply Current	Iccq	-	350	500	μΑ	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I_{IN+}	-	3.0	10	μΑ	$V_{IN} = 5V, SD^* = 0V$
Logic "0" Input Bias Current	I _{IN-}	-	-	5.0	μΑ	$V_{IN} = 0V, SD^* = 5V$
V _{CC} Supply Undervoltage Positive Going Threshold	V_{CCUV+}	8.0	8.9	9.8	V	-
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV} -	7.4	8.2	9.0	٧	-
Output High Short Circuit Pulsed Current	I _{O+}	130	290		mA	V _O = 0V, PW ≤ 10μs
Output Low Short Circuit Pulsed Current	I _{O-}	270	600	-	mA	V _O = 15V, PW ≤ 10μs

Note:

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Turn-On Propagation Delay	ton		680	820	ns	$V_S = 0V$
Turn-Off Propagation Delay	toff	-	150	220	ns	$V_S = 600V$
Shutdown Propagation Delay	tsp	_	160	220	ns	_
Delay Matching, HO and LO Turn-On/Turn-Off	t _{DM}	_	-	60	ns	_
Turn-On Rise Time	t _R	-	70	170	ns	$V_S = 0V$
Turn-Off Fall Time	te	-	35	90	ns	$V_S = 0V$
Deadtime: t _{DT LO-HO} & t _{DT HO-LO}	t _{DT}	400	520	650	ns	-

^{7.} The V_{IN} and I_{IN} parameters are applicable to the two logic pins: IN and SD*. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.



Timing Waveforms

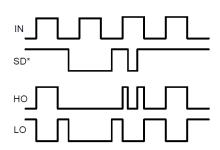


Figure 1. Input / Output Timing Diagram

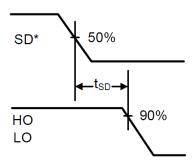
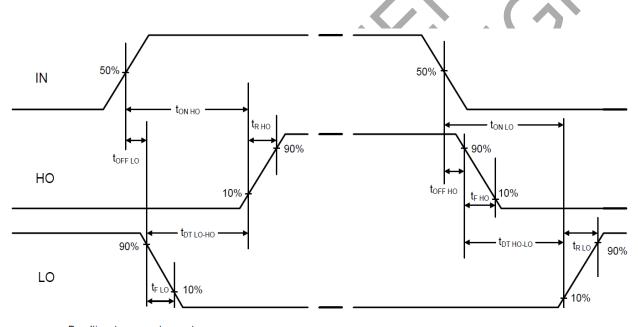


Figure 2. Shutdown Waveform Definition



 $\begin{aligned} \text{Deadtime } t_{\text{DT LO-HO}} &= t_{\text{ON HO}} \text{--} t_{\text{OFF LO}} \\ t_{\text{DT HO-LO}} &= t_{\text{ON LO}} \text{--} t_{\text{OFF HO}} \end{aligned}$

Deadtime matching $t_{MDT} = t_{DT LO-HO} - t_{DT HO-LO}$

 $\begin{aligned} & \text{Delay matching} \\ t_{\text{DM OFF}} &= t_{\text{OFF LO}} - t_{\text{OFF HO}} \\ t_{\text{DM ON}} &= t_{\text{ON LO}} - t_{\text{ON HO}} \end{aligned}$

Figure 3. Switching Time Waveform Definitions



Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

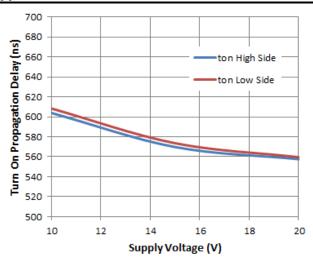


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

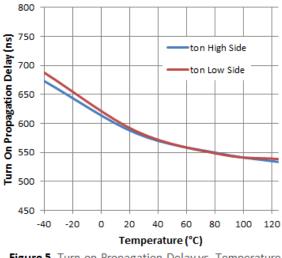


Figure 5. Turn-on Propagation Delay vs. Temperature

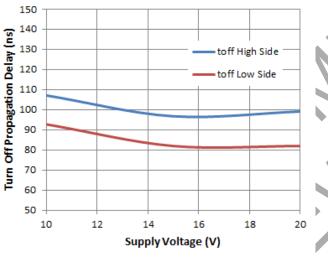


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

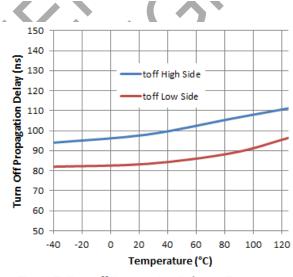


Figure 7. Turn-off Propagation Delay vs. Temperature

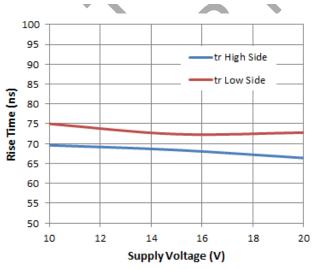


Figure 8. Rise Time vs. Supply Voltage

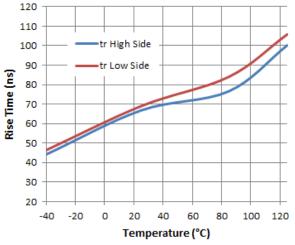


Figure 9. Rise Time vs. Temperature

60

50

120



600

500

400

300

200

0

10

12

Quiescent Current (μΑ)

Typical Performance Characteristics (Cont.)

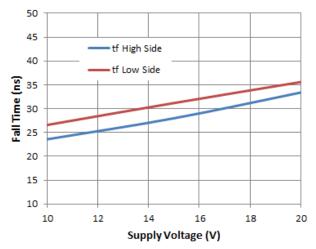
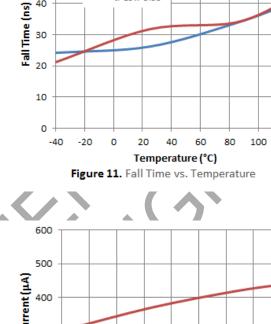


Figure 10. Fall Time vs. Supply Voltage



tf High Side

tf Low Side

600 500 400 100 -40 -20 0 20 40 60 80 100 120 Temperature (°C)

Figure 12. Quiescent Current vs. Supply Voltage

Supply Voltage (V)

16

14

IBSq

18

20

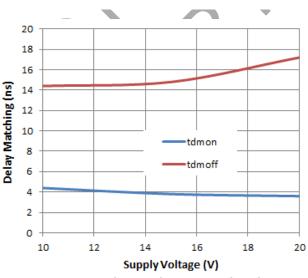


Figure 14. Delay Matching vs. Supply Voltage

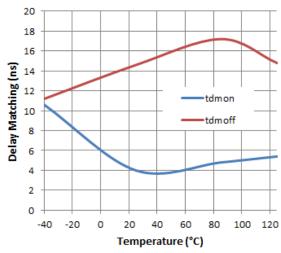


Figure 13. Quiescent Current vs. Temperature

Figure 15. Delay Matching vs. Temperature



Typical Performance Characteristics (Cont.)

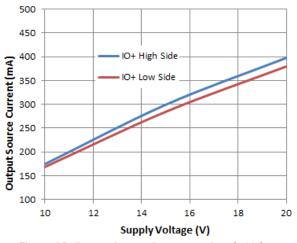


Figure 16. Output Source Current vs. Supply Voltage

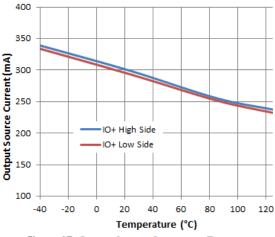


Figure 17. Output Source Current vs. Temperature

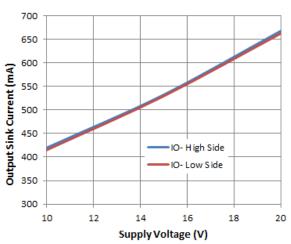


Figure 18. Output Sink Current vs. Supply Voltage

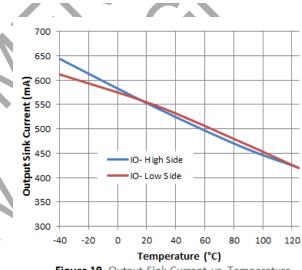


Figure 19. Output Sink Current vs. Temperature

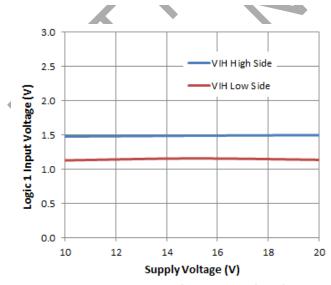


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

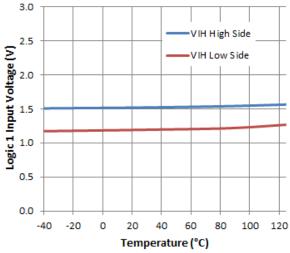


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (Cont.)

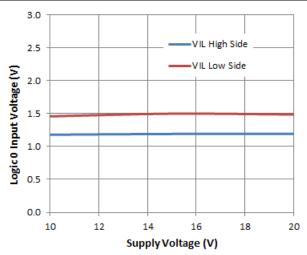


Figure 22. Logic O Input Voltage vs. Supply Voltage

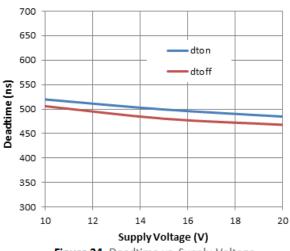


Figure 24. Deadtime vs. Supply Voltage

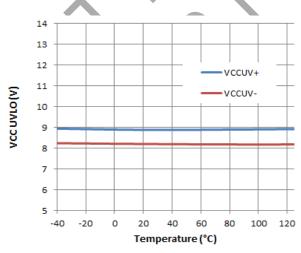


Figure 26. VCC UVLO vs. Temperature

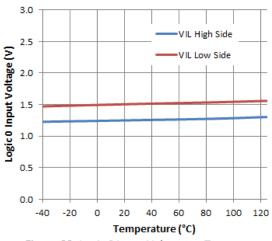


Figure 23. Logic 0 Input Voltage vs. Temperature

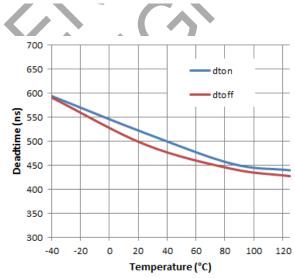


Figure 25. Deadtime vs. Temperature

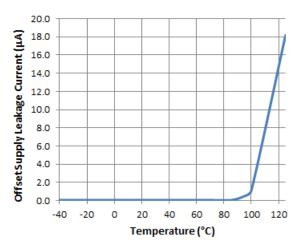


Figure 27. Offset Supply Leakage Current vs. Temperature

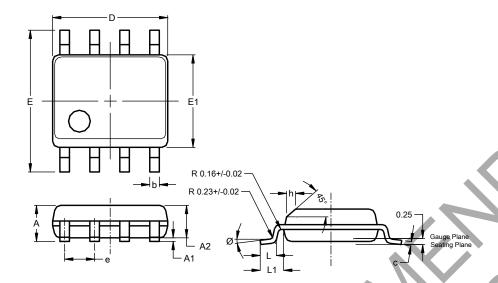


DGD2104

Package Outline Dimensions

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SO-8 (Type TH)

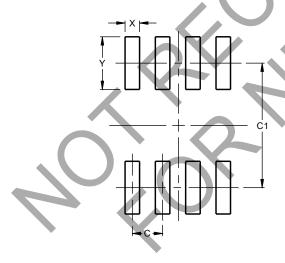


SO-8 (Type TH)					
Dim	Min	Max	Тур		
Α	1.35	1.75			
A1	0.10	0.25			
A2			1.45		
b	0.35	0.51			
С	c 0.190				
D	D 4.80		4.90		
Е	5.80	6.20	6.00		
E1	E1 3.80		3.90		
е		-	1.27		
h	0.25	0.50	-		
L	L 0.41				
L1		1	1.04		
Ø	0°	8			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH



Dimensions	Value (in mm)
C	1.27
C1	5.20
Х	0.60
Υ	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

NOT RECOMMENDED FOR NEW DESIGN USE DGD2104M



DGD2104

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